

~~ABSTRACT~~

ENCAPSULATED SURFACE ACOUSTIC WAVE COMPONENT AND METHOD OF COLLECTIVE FABRICATION

The invention relates to a new type of encapsulated surface acoustic wave component and to a method for the batch production of such components.

The component comprises a surface acoustic wave device on the surface of a substrate. The encapsulation package furthermore comprises the substrate, a first layer located on the substrate and hollowed out locally at least at the level of the active surface of the surface acoustic wave device, a printed circuit covering entire first layer and conductive via holes going through the unit formed by the first layer and the printed circuit so as to provide for the electrical connection of the surface acoustic wave device from the exterior.

Figure 3

Sub
A2

[illegible]